



The IET Hong Kong Branch
Manufacturing and Industrial Engineering Section Committee
(MIESC) 07/08

Safety Standards Forum 2008

Organized by: Manufacturing and Industrial Engineering Section (MIESC), IET Hong Kong Branch

Co-organized by: (1) Department of Industrial and System Engineering, Hong Kong Polytechnic University

(2) Department of Engineering, Hong Kong Institute of Vocational Education (Tsing Yi)

Supporting Organizations:

- Manufacturing & Industrial Engineering Alumni Association, The Hong Kong Polytechnic University
- The Institution of Measurement and Control - Hong Kong Section
- The Hong Kong Institution of Engineers – Safety Specialist Committee



Department of
Industrial & Systems Engineering
工業及系統工程學系



THE HONG KONG POLYTECHNIC
UNIVERSITY
MANUFACTURING AND INDUSTRIAL
ENGINEERING ALUMNI ASSOCIATION



Department of Engineering
(Tsing Yi)



Safety Specialist Committee

Seminar: Safety Standard Forum 2008

Date : 17 May 2008 (Saturday)

Time : 9:00 a.m. – 12:30 p.m.

Venue: AG710 Hong Kong Polytechnic University, Kowloon, Hunghom



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Contents:

Product Safety is the hottest topic in the manufacturing industry. Many different types of products were found not to comply with the safety standards/regulations. The custom and the buyers continue to closely monitor their vendors. EU and USA proposed many new regulations to regulate the safety of products.

The forum invited some expertise in Fire Safety Products, Electronic Product, Toys and Children Products, to introduce the change and trend of safety standards.

Language: Cantonese with English Terminology

Fee: Free of charge

Target Audiences:

- Participants (limited to 100, registration is required)
- Members of IET (first priority)
- Members of supporting organizations
- Industrialists, technological, professional and innovative personnel,
- Other professionals (e.g. engineers,)
- Students and Public interested personnel



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Format of the Seminar:

Period	Activities –
9:00 am – 9:30 am	Registration 登記
9:30 am – 9:35 am	Welcome Address Ir Jolly Wong, Vice Chairman, The Institution of Engineering and Technology Hong Kong Branch.
9:35 am – 9:40 am	Opening Speech Ir Albert C. K Choi, Programme Leader, B Eng, Product Engineering with Marketing (Part Time), ISE Department, HK PolyU.
9:40 am – 10:30 am	First Session Hong Kong Practices for the Fire Safety Products Ir C.K Cheung, Committee member - Hong Kong Institution of Steel Construction, President – Hong Kong Institution of Certified Auditors.
10:30am – 11:10am	Second session What are EMC, EMC testing and R&TTE testing? Mr. Derek Leung, Project Manager, Technical Certifier (EMC & Telecom), TUV Rheinland Hong Kong Ltd. Founding and committee member of EMC Chapter, IEEE-Hong Kong.
11:10am – 11:30am	Coffee Break 茶點招待
11:30am – 12:10pm	Third session Recent Changes of Safety Standard for Toys and Children Products Mr. Kevin Chan, Assistant Manager – Physical & Mechanical Laboratory, Specialized Technology Resources (H.K.) Ltd.
12:10pm – 12:25pm	Panel Discussion Chaired by Ir Albert C. K Choi, Programme Leader, B Eng, Product Engineering with Marketing (Part Time), ISE Department, HK PolyU.
12:25pm – 12:30pm	Closing Remarks, Souvenir Presentations and Group Photos Ir M. K. Lam, Chairman, Manufacturing and Industrial Engineering Section, The Institution of Engineering and Technology Hong Kong Branch.



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Registration for Safety Standards Forum 2008:

Seats are limited (first come first serve) and registration is necessary. For all participants, please submit Reply Form to us via fax (2120 8323) or email to imc.slmak@gmail.com

The event activity can be accessed at <http://www.theiet.org.hk> or <http://www.instmc.org.hk>

Reply Form

Name: _____

Organization: _____

Contact Tel: _____

Mobile: _____

Fax: _____

Email: _____

Signature: _____

Date: _____